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APPLICATION NO.		FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.		
10/792,244 03/03		03/03/2004	David R. Hembree	3592.10US 3976 (97-0321.10/US)			
24247	7590	12/14/2004		EXAM	EXAMINER		
TRASK B P.O. BOX 2			MITCHELL, JAMES M				
SALT LAKE CITY, UT 84110				ART UNIT	PAPER NUMBER		
				2813			
			DATE MAILED: 12/14/2004				

Please find below and/or attached an Office communication concerning this application or proceeding.

		Applicati	on No	Applicant(s)				
Office Action Summary								
			14	HEMBREE, DAVID R.				
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	The MAILING DATE of this commun	James M.		2813	dress			
Period fo		.out.on appoulo on the		on coponacines au	u, 000			
THE - Exte after - If the - If NC - Failt Any	ORTENED STATUTORY PERIOD F MAILING DATE OF THIS COMMUNI nsions of time may be available under the provisions SIX (6) MONTHS from the mailing date of this comn period for reply specified above is less than thirty (3 period for reply is specified above, the maximum st tre to reply within the set or extended period for reply reply received by the Office later than three months a ed patent term adjustment. See 37 CFR 1.704(b).	CATION. of 37 CFR 1.136(a). In no ev nunication. 0) days, a reply within the stat atutory period will apply and w will, by statute, cause the app	ent, however, may a reply be tim utory minimum of thirty (30) days ill expire SIX (6) MONTHS from lication to become ABANDONEI	nely filed s will be considered timely the mailing date of this co D (35 U.S.C. § 133).				
Status								
1)⊠	Responsive to communication(s) file	ed on <u>17 May 2004</u> .						
2a)□		2b)⊠ This action is r	on-final.					
3)□								
	closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213.							
Disposit	ion of Claims							
· <u> </u>	)⊠ Claim(s) <u>1-10</u> is/are pending in the application.							
	4a) Of the above claim(s) is/are withdrawn from consideration.							
	Claim(s) is/are allowed.							
	Claim(s) <u>1-10</u> is/are rejected.		•					
/)∐	Claim(s) is/are objected to.	tion and/or alaction r	oguirom ont	,				
ابا(8	Claim(s) are subject to restrict	xion and/or election r	equirement.	Samuel				
Applicat	ion Papers			×.rs				
9)[	The specification is objected to by th	e Examiner.	•	15 M				
10)☐ The drawing(s) filed on is/are: a)☐ accepted or b)☐ objected to by the Examiner.								
	Applicant may not request that any object	ction to the drawing(s) I	oe held in abeyance. See	∍ 37 CFR 1.85(a).				
	Replacement drawing sheet(s) including	•	J., ,		` '			
11)[	The oath or declaration is objected to	b by the Examiner. No	te the attached Office	Action or form PT	O-152.			
Priority (	ınder 35 U.S.C. § 119							
	Acknowledgment is made of a claim  All b) Some * c) None of:  Certified copies of the priority	documents have bee	n received.					
	2. Certified copies of the priority		• •					
	3. Copies of the certified copies			ed in this National	Stage			
* (	application from the Internatio See the attached detailed Office actio	•		•d				
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Attachmen	t(s)							
1) Notic	e of References Cited (PTO-892)	•	4) Interview Summary					
	e of Draftsperson's Patent Drawing Review (P mation Disclosure Statement(s) (PTO-1449 or		Paper No(s)/Mail Da 5) Notice of Informal P		)_152)			
Pape	r No(s)/Mail Date <u>3/3/04, 8/30/04</u> .	F 1 Orabido)	6) Other:	a.s.r. application (i Te				

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## **DETAILED ACTION**

This office action is in response to the preliminary amendment filed May 17, 2004.

## Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 1-10 are rejected under 35 U.S.C. 103(a) as being unpatentable over Bernier et al. (U.S. 6,069, 023) in combination with Mcdonald Jr. et al. (U.S. 5,905,638).

Bernier (Fig 6) discloses (cl. 1,4,6, 9) a semiconductor assembly comprising: a substrate (304) having a plurality of circuits (310) on a portion of a surface thereof; a semiconductor die (302) having a plurality of inherent bond pads (not labeled, chip surface contacting item 308) located on an active surface thereof (flip chip configuration) and having a back side (top portion) surface; a plurality of solder balls (308) connecting at least a portion of the plurality of bond pads of the semiconductor die to at least a portion of the plurality of circuits of the substrate; one of a glob top material and a low viscosity polymeric material ("epoxy" shown as 220) filling any space between the substrate and the semiconductor die; is compliant (i.e. "flexible"; absract), adhesive, and filled with a thermally conductive material (Claim 14 of Bernier); and a heat sink cap (320) covering the adhesive, the semiconductor die, the plurality of solder balls, and a portion of the substrate, the heat sink cap contacting at least a portion of the adhesive;

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(cl. 2, 5, 7, 10) with the heat sink cap including fins (protruding portion of 320) wherein the compliant adhesive is silicone filled with a thermally conductive material (Claim 14 of Bernier).

Bernier does not appear to shows gel elastomer that is a cross-linked silicone filled with a thermally conductive material that forms a gel elastomer.

Macdonald utilizes a silicone gel elastomer (col. 5, Lines 1-5) that is inherently cross-linked (i.e. applicant defines gel elastomer as being cross linked silicone).

It would have been obvious to one of ordinary skill in the art to incorporate a silicone gel elastomer in order to enhance thermal conductivity as taught by MacDonald (Co. 5, Lines 1-5).

## Conclusion

The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. MacDonald Jr. et al. (U.S. 5,905,638).

The prior art in McDonald Jr. discloses the use of a gel elastomer between silicone gel elastomer between a chip and heat sink.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to James M. Mitchell whose telephone number is (571) 272-1931. The examiner can normally be reached on M-F 8:00-4:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Carl Whitehead Jr. can be reached on (571) 272-1702. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

√mm Octro

Octrober 22, 2004

CARL WHITEHEAD JR.

SUPERVISORY PATENT EXAMINER

**TECHNOLOGY CENTER 2800**